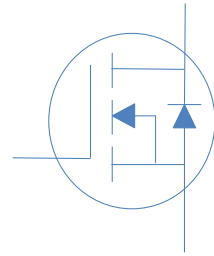
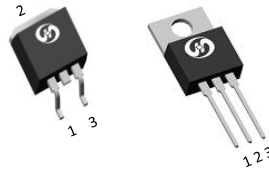


150V N-Ch Power MOSFET

V_{DS}		150	V
$R_{DS(on),typ}$	TO-263	16.0	m
$R_{DS(on),typ}$	TO-220	16.3	m
I_D (Silicon Limited)		59	A



Part Number	Package	Marking
HGB195N15S	TO-263	GB195N15S
HGP195N15S	TO-220	GP195N15S

Absolute Maximum Ratings at $T_J=25^{\circ}\text{C}$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^{\circ}\text{C}$	59	A
		$T_C=100^{\circ}\text{C}$	42	
Drain to Source Voltage	V_{DS}	-	150	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	180	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.4\text{mH}, T_C=25^{\circ}\text{C}$	80	mJ
Power Dissipation	P_D	$T_C=25^{\circ}\text{C}$	150	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 175	$^{\circ}\text{C}$

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	R_{JA}	46	$^{\circ}\text{C}/\text{W}$
Thermal Resistance Junction-Case	R_{JC}	1	$^{\circ}\text{C}/\text{W}$

Electrical Characteristics at $T_J=25^\circ\text{C}$ (unless otherwise specified)

Static Characteristics

Par

Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\text{ A}$			
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\text{ A}$	2	3	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS}=0V, V_{DS}=150V, T_J=25^\circ\text{C}$	-	-	1
Gate to Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100
Drain to Source on Resistance	$R_{DS(on)}$		-	16	19.2 m
Transconductance	g_{fs}	$V_{DS}=5V, I_D=20A$	-	55	- S
Gate Resistance	R_G	$V_{GS}=0V, V_{DS}\text{ Open}, f=1\text{MHz}$	-	2.2	-

Dynamic Characteristics

Input Capacitance	C_{iss}		-	1960	-
Output Capacitance	C_{oss}	$V_{GS}=0V, V_{DS}=75V, f=1\text{MHz}$	-	130	
Reverse Transfer Capacitance	C_{riss}		-	8	-
Total Gate Charge	$Q_g(10V)$		-	25	-
Gate to Source Charge	Q_{gs}	$V_{DD}=75V, I_D=20A, V_{GS}=10V$	-	9	-
Gate to Drain (Miller) Charge	Q_{gd}		-	3	-
Turn on Delay Time	$t_{d(on)}$		-	9	-
Rise time	t_r	$V_{DD}=75V, I_D=20A, V_{GS}=10V,$	-	8	- ns
Turn off Delay Time	$t_{d(off)}$	$R_G=10\text{ }\Omega$	-	15	- ns
Fall Time	t_f		-	9	-

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_F=20A$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}		-	60	-	ns
Reverse Recovery Charge	Q_{rr}	$V_R=75V, I_F=20A, dI_F/dt=100A/\text{s}$	-	120	-	nC

Fig 1. Typical Output Characteristics

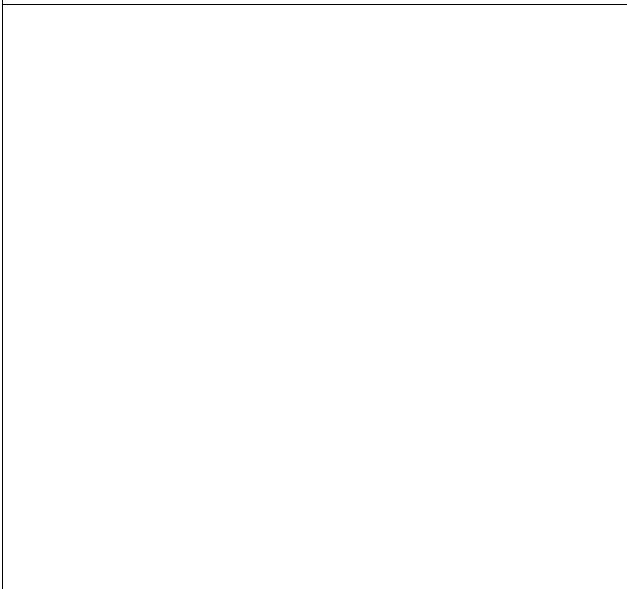


Figure 2. On-Resistance vs. Gate-Source Voltage

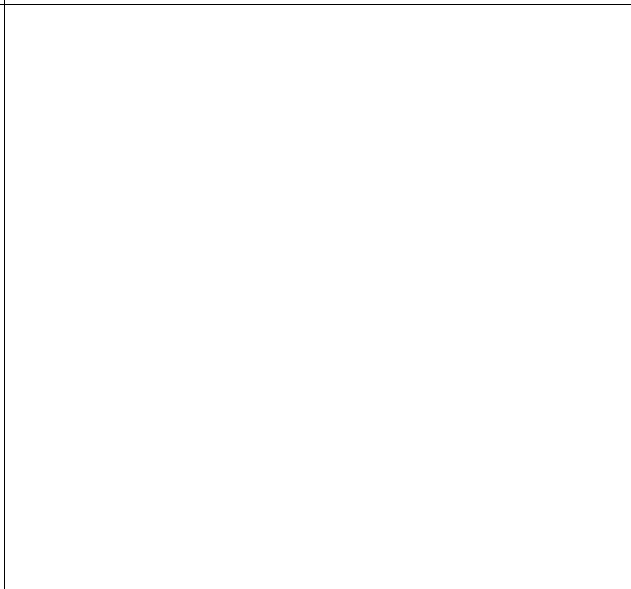


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

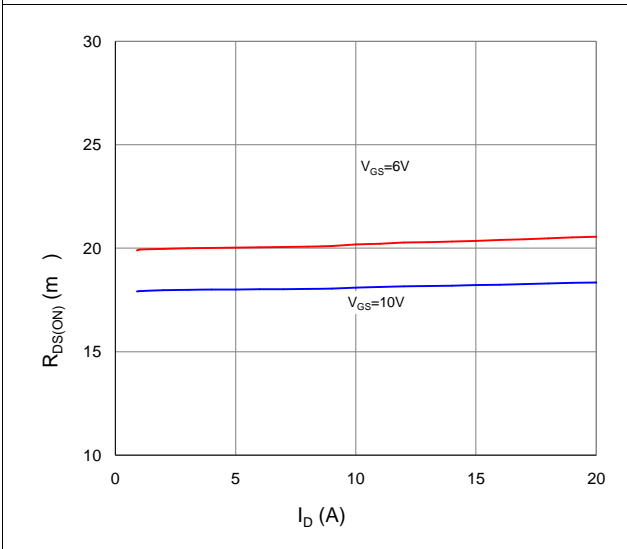


Figure 4. Normalized On-Resistance vs. Junction Temperature

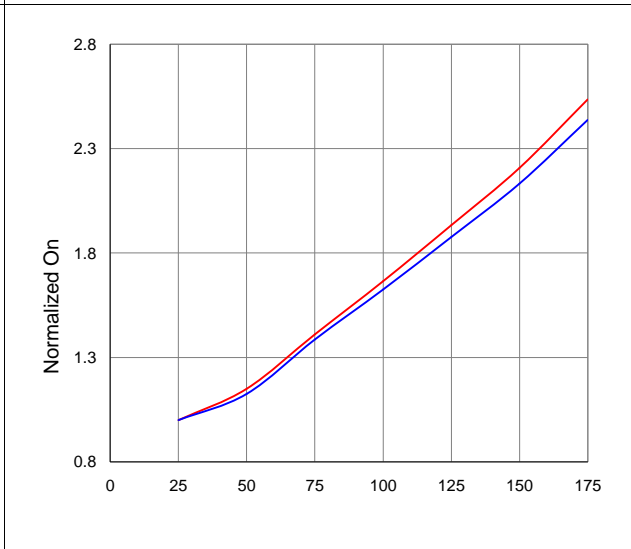


Figure 5. Typical Transfer Characteristics

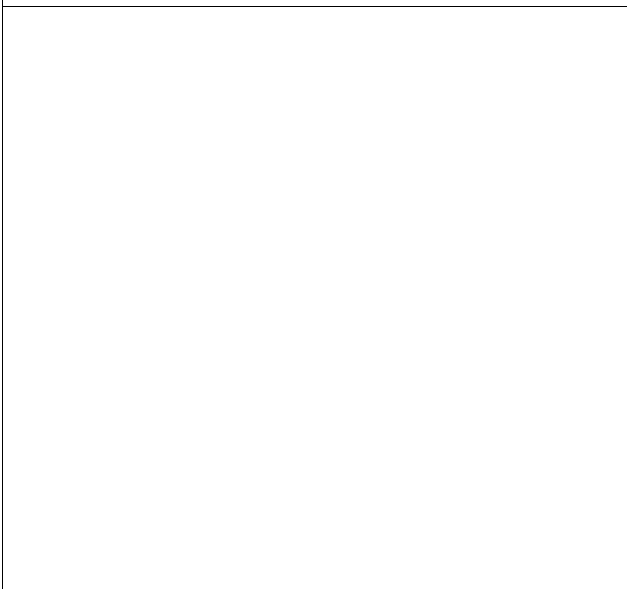


Figure 6. Typical Source-Drain Diode Forward Voltage

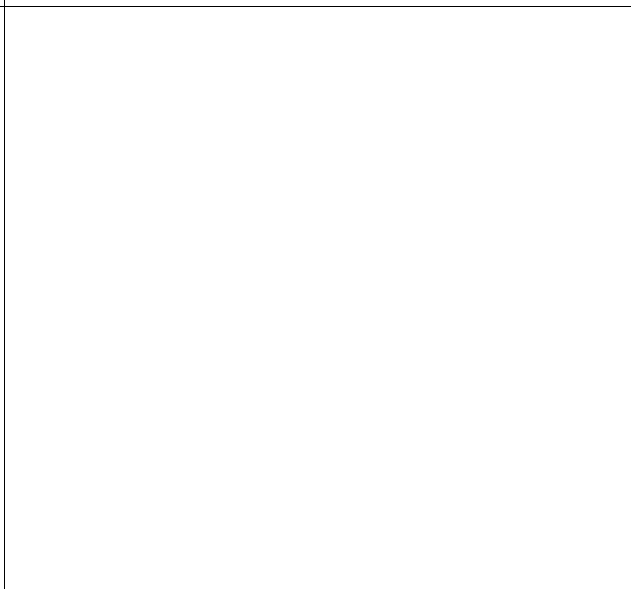


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

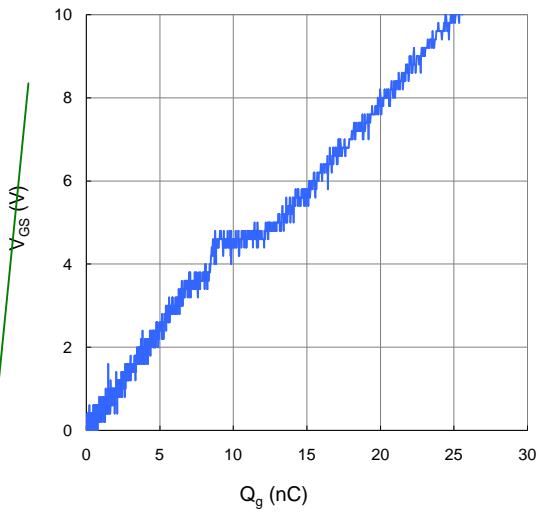


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

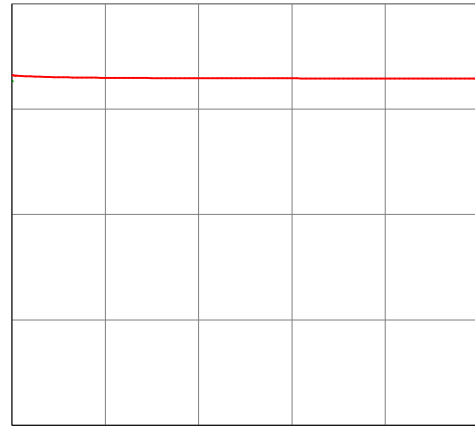
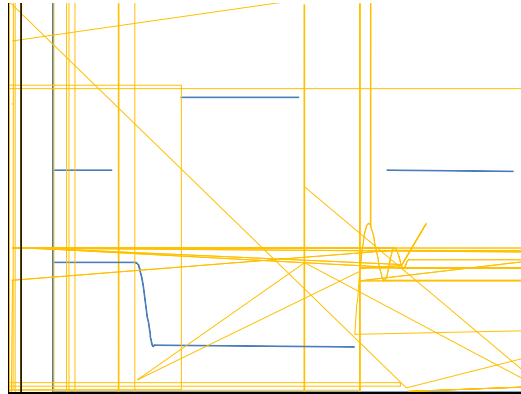
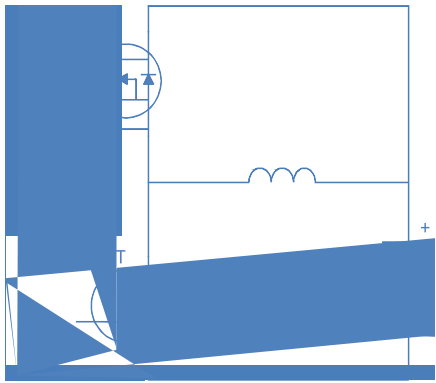


Figure 9. Maximum Safe Operating Area

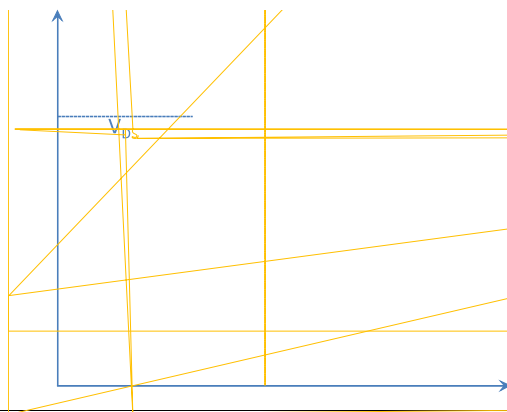
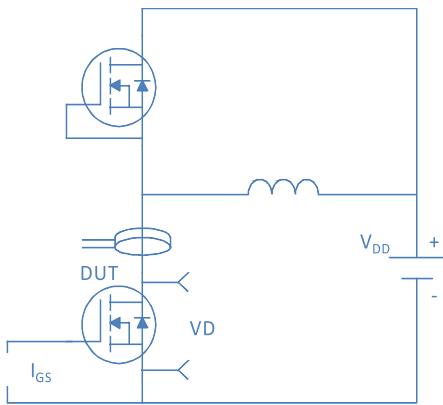
Figure 10. Maximun Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient

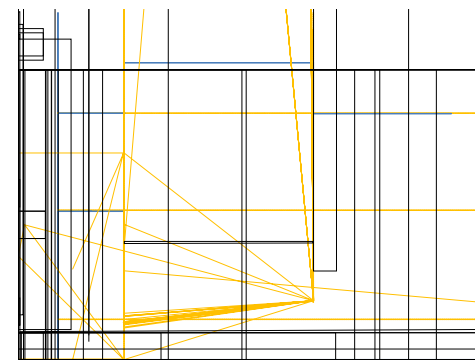
Inductive switching Test



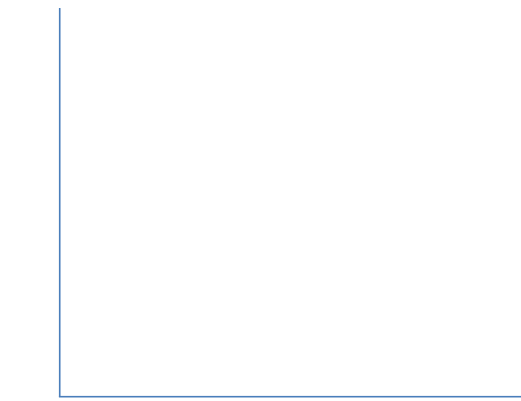
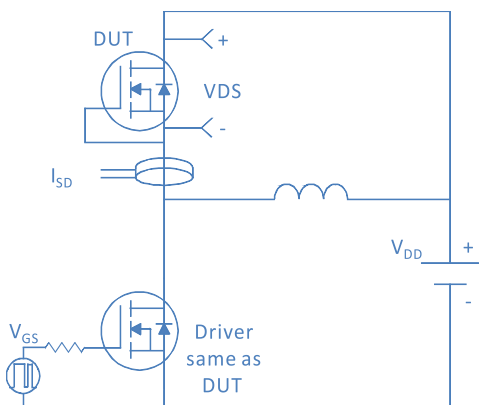
Gate Charge Test



Uclamped Inductive Switching (UIS) Test

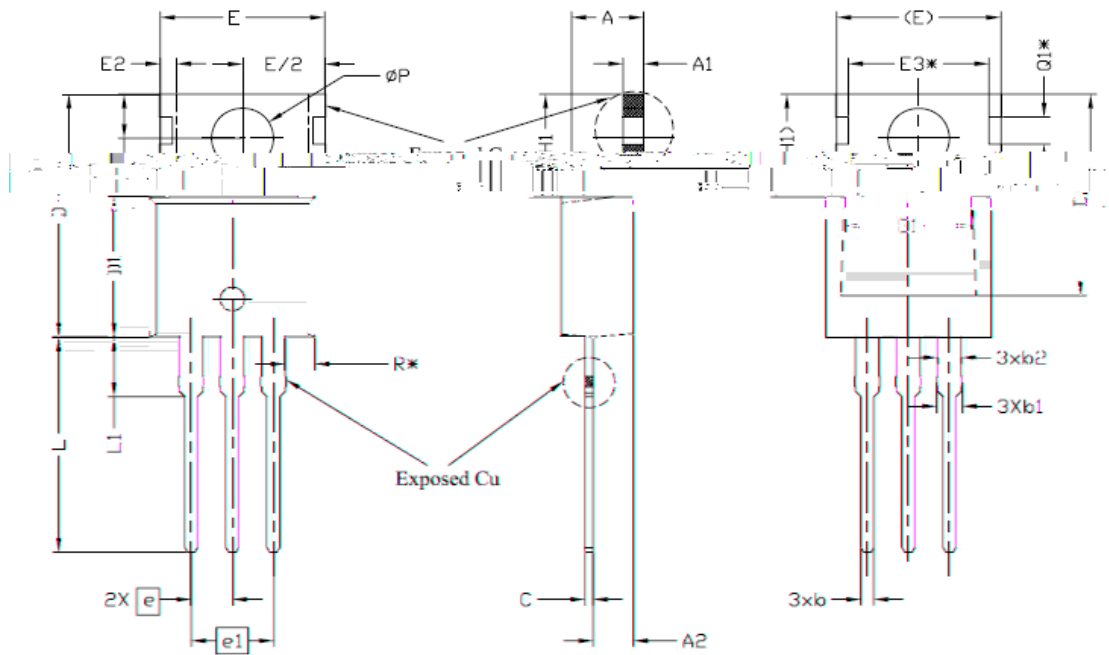


Diode Recovery Test



Package Outline

TO-220, 3 leads



SYMBOL	DIMENSIONS			NOTES
	MIN.	NOM.	MAX.	
A1	0.12	0.15	0.18	0.149
A2	0.25	0.40	0.50	0.30
E	0.15	0.20	0.25	0.20
E1	1.50	1.50	1.50	1.50
E2	1.70	1.70	1.70	1.70
E3	0.45	0.45	0.45	0.45
e	14.50	15.20	16.00	16.00
e1	3.30	3.80	4.00	4.00
e2	13.80	14.70	15.50	15.50
e3	3.98	4.18	4.38	4.38
e4	6.38	7.20	8.00	8.00
e5	1.2			1.26
e6			0.12±0.01	
e7			2.34±0.05	
e8			±0.05±0.05	
5.0	11.5	6.30	6.45	6.30
6.0		13.47	13.72	13.67
7.0		3.80	3.80	4.00
8.0		5.25	5.25	5.25
9.0		3.80	3.80	3.80
10.0			1.25±0.1	
11.0			1.82±0.1	

